

Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

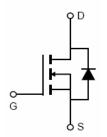
Application

- DC/DC Converter
- •Ideal for high-frequency switching and synchronous rectification

General Features

- V_{DS} =100V, I_D =280A $R_{DS(ON)}$ =1.85m Ω , typical@ V_{GS} =10V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 175 °C operating temperature
- Pb-free lead plating





Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST10N018-T7	VST10N018	TO-247	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	100	V	
Gate-Source Voltage	V _G s	±20	V	
Drain Current-Continuous	I _D	280	А	
Drain Current-Continuous(T _C =100 °C)	I _D (100°C)	200	А	
Pulsed Drain Current	I _{DM}	980	А	
Maximum Power Dissipation	P _D	365	W	
Derating factor		2.43	W/°C	
Single pulse avalanche energy (Note 4)	E _{AS}	2784	mJ	
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	°C	

Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	0.41	°C/W	
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Electrical Characteristics (T_C=25 ℃ unless otherwise noted)

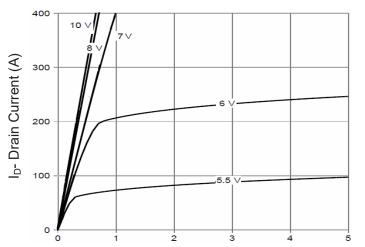
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•	•		•
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	100		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 2)			•	•		•
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.0	3.0	4.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =140A	-	1.85	2.3	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =140A		200	-	S
Dynamic Characteristics (Note3)			•	•		•
Input Capacitance	C _{lss}	V _{DS} =50V,V _{GS} =0V,	-	17000	-	PF
Output Capacitance	C _{oss}		-	1500	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	77	-	PF
Switching Characteristics (Note 3)			•			•
Turn-on Delay Time	t _{d(on)}	V_{DD} =50V, I_{D} =140A V_{GS} =10V, R_{G} =1.6 Ω	-	37	-	nS
Turn-on Rise Time	t _r		-	29	-	nS
Turn-Off Delay Time	t _{d(off)}		-	82	-	nS
Turn-Off Fall Time	t _f		-	34	-	nS
Total Gate Charge	Qg	V -F0V/I -440A	-	252	-	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=50V,I_{D}=140A,$ $V_{GS}=10V$	-	72		nC
Gate-Drain Charge	Q _{gd}	VGS-10V	-	63		nC
Drain-Source Diode Characteristics			•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =140A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	280	Α
Reverse Recovery Time	t _{rr}	$T_J = 25^{\circ}C$, $I_F = 140A$	-	105	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note2)}$	-	290	-	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 3. Guaranteed by design, not subject to production
- 4. EAS condition : Tj=25 $^{\circ}\text{C}$,V_DD=50V,V_G=10V,L=0.5mH,Rg=25 Ω

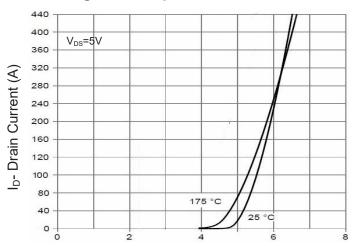


Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

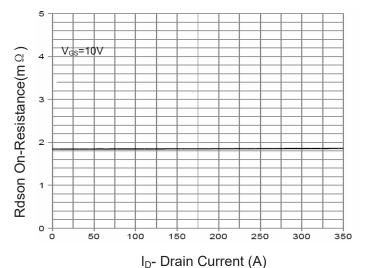
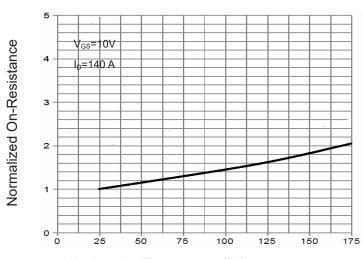
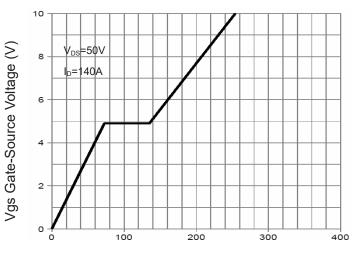


Figure 3 Rdson- Drain Current

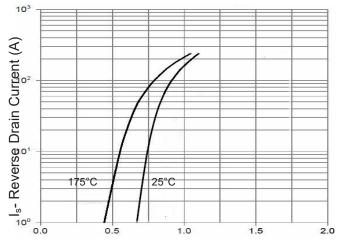


T_J-Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature



Qg Gate Charge (nC)
Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward



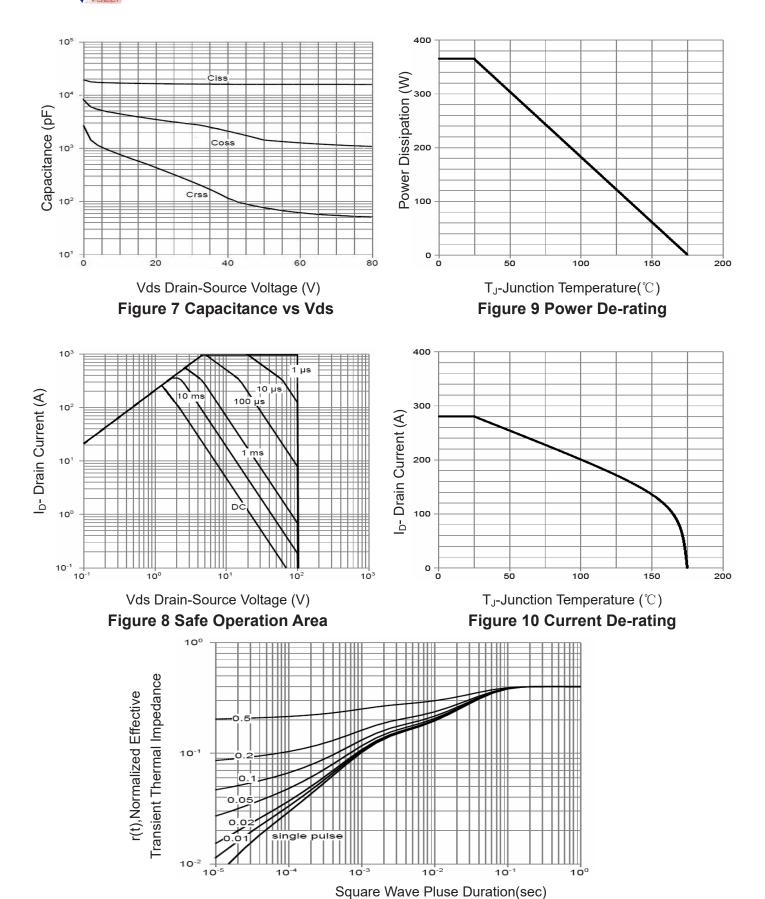


Figure 11 Normalized Maximum Transient Thermal Impedance